

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **08/26/2022**

Details for "LM1085ISX-ADJ"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM1085ISX-ADJ	SNPB	Level-3-235C-168 HR	Texas Instruments Electronics	KTT 3	10.2 x 9 x 4.5	1456.4

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.811759	99.993102	999931	0.055739	557
Copper and Its Alloys	Iron	7439-89-6	0.000007	0.000862	9	0	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000012	0.001478	15	0.000001	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000003	0.00037	4	0	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.00001	0.001232	12	0.000001	0
Precious Metals	Silver	7440-22-4	0.000024	0.002956	30	0.000002	0
Sub-Total			0.811815	100	1000000	0.055743	557
Die Attach Adhesive							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	3.555317	95.500001	955000	0.244125	2441
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.074457	2.000003	20000	0.005113	51
Precious Metals	Silver	7440-22-4	0.093071	2.499997	25000	0.006391	64
Sub-Total			3.722845	100	1000000	0.255628	2556
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	643.242325	99.55	995500	44.167998	441680
Copper and Its Alloys	Phosphorus	7723-14-0	0.064615	0.01	100	0.004437	44
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.969225	0.15	1500	0.066551	666
Precious Metals	Silver	7440-22-4	1.873835	0.29	2900	0.128666	1287
Sub-Total			646.15	100	1000000	44.367652	443677
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	1.92	15	150000	0.131836	1318
Other Nonferrous Metals and Alloys	Tin	7440-31-5	10.88	85	850000	0.747071	7471
Sub-Total			12.8	100	1000000	0.878907	8789
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	701.091208	89	890000	48.14017	481402
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	23.632288	3	30000	1.622702	16227
Thermoplastics	Epoxy	85954-11-6	63.019434	8	80000	4.327206	43272
Sub-Total			787.74293	100	1000000	54.090079	540901
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	5.126234	100	1000000	0.351991	3520
Sub-Total			5.126234	100	1000000	0.351991	3520
Total			1456.353824			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 08/26/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.